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PH4 ISPL (ATEC) (CU) MBOI Data

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Manufacturing Bill of Information (MBOI)			
Part Number	MC74HC595ADR2G-ASY	Part Type	Assembly Part
Site Name Loc Cod	PH4 ISPL (ATEC) CU	File Name	PH4_MC74HC595ADR2G_MC74HC595ADR2G-ASY_ASY
Flags	Non Safe Launch Item No Global Hold Flag	Part Qual Target Market:	U Unspecified
Part Version	1	Part Version Date-Time	2021-DEC-15 10:38:34 (GMT +7)

Orderable Part Section - OPN

Part Number Desc	MC74HC595ADR2G LOG CMOS SHIFT REG 8BIT	Market PN	MC74HC595ADR2G
Lifecycle Phase	Production	Part Class Desc	AA ASSEMBLED AND TESTED
Marketing Product Lifecycle	Follow Part Lifecycle	Part Sub Type	OPN
Part Release Status Desc	MC-M Mass Production	Part Usage	STD
Case Outline (CO)	751B-05	PAL4 Code Desc	
Product Data Sheet	MC74HC595A-D.PDF		
ERP Resource Code - ASY Desc	7047 SOIC 16 COPPER PB FREE H	OPN Part Qual Target Market	U Unspecified
Packing Configuration	SOIC-16_751B_REEL_2500_FBG5000	Eng Package Type	SOIC-16

Assembly_Part_Section - ASY

Part Number	MC74HC595ADR2G-ASY	Description	ASSY RAWSTOCK
Lifecycle Phase	Production	Part Usage	STD
Part Release Status Desc	MC-M Mass Production	Part Sub Type	ASY
PAL4 Code Desc		ERP Resource Code - ASY Desc	7047 SOIC 16 COPPER PB FREE H
Part Qual Target Market	U Unspecified		
Case Outline (CO)	751B-05	Package Type	SOIC-16
ECAT Override		Actual Lead Count	16
Package Assembly Platform	SOSM - Small Outline Surface Mount	Assembly Baseline Spec	
Assembly Process Flow Spec		Assembly Spec(s) - Global	
Lot Processing Restrictions	Standard		
ITAR Part Flag	N	Customs Configuration	8542.39.0001
Customs ECCN Code	EAR99	Customer Consigned Flag	N
Compressed?		Compressed Part Number	
Wettable Process Type		Wettable Flank Flag	
Site Notes			

BOM Components

Alternate 001	Part Number	Part Sub Type	Line	Preference	Group	Qty	Description	Lifecycle Phase
Primary Die	DBTHC595ABK10	WDQ	001	01	0	1	TOWER HSL DIE	Production
	Die Size (X + Y W/Scribe Street): 710 x 651							PDPW : 32851
Package Kit	N96938G006	PKT	002	01	0	1	PKGKIT SOIC 16 CU (PH4)	Production
	Piece Parts							
	1360100040	FRAME	010	01	0	1	LF 16Lds NB 1.08x1.08vmm Pad, Spot Ag, STAMP	Production
	1010150057	EPXY	020	01	0	0.000324	DA Sumitomo CRM-1076WB	Production
	1360162001	WIRE	030	01	0	0.02482	BW Maxsoft 0.8 mil Cu Wire	Production
	1360194006	MOLD	040	01	0	0.46667	MC SUMITOMO G600 13MM X 3.9G	Production

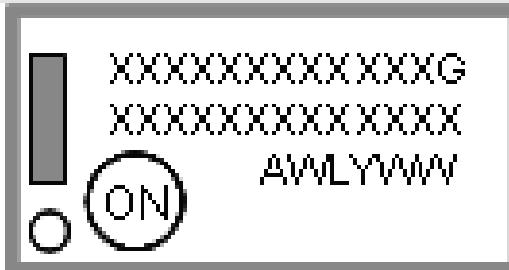
Marking Header Section

Marking Style Configuration	SOIC-PSOP_2L_26C_ICSTD	
Standard Marking Flag		
Pb Free Mark Character Flag		

Front Side Marking

Line1:HC595AG
Tracecode:Y(WLYWW)

Pin 1 Bar
or
Pin 1 Dot

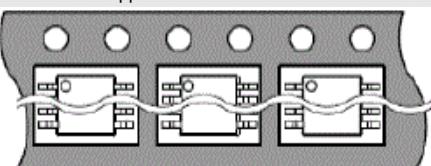
**Marking Details Section**

Trace Code Coding Std	ON_STD_031C : A(WL)(YWW) : (A01)(L21)(Y03L)(W03L)	Trace Code Coding Custom	
Trace Code Legend - Front	[A: Assembly Site, WL: Wafer Lot Number, Y: Year of Production, Last Number, WW: Work Week Number]		
Trace Code Legend - Back			
Trace Code Spec	12MON00232D LF	Part Marking Source	PDM System
Part Marking Image/CAD Document		Marking Style Image Document	18AON90176E O
Custom Logo Document		ON Logo Document	18AON77167F O
Final Test Specification	48ARM92243A W		

OPN Packing Section

PCQ Container Desc	REEL Tape and Reel	PCQ Quantity	2500
MPQ Container Desc	REEL Tape and Reel	MPQ Quantity	2500
Intermediate Full Box Container Type Intermediate Box Container Size Intermediate Full Box Container Quantity	 5000	Intermediate Full Bag Container Type Intermediate Bag Container Size Intermediate Full Bag Container Quantity	

Pin 1 Toward Upper Left

**Labeling Section**

MSL	1	MSL Temperature	260
Pb Free Leads Flag	Y	Halide Free Flag	Y
Pb Free Die Attach Flag	Y	Lead Finish Category (eCAT)	e3

Document Group Section

Document Num	Revision	Release Date	Title
12MON00232D	LF	07-Oct-21	Standard Marking for Integrated Circuits
12MON01117D	AB	01-Oct-21	Quality Assurance Inspection and Testing Sample Plan
12MON03769D	W	28-Sep-20	External Visual Inspection Criteria
12MON49004E	AB	26-May-20	Subcontractors Bar Code Labeling
12MRB17500B	FJ	26-Oct-21	Finished Goods Packing and Long Term Storage Procedure
12MRM92695A	AC	04-May-21	Lot Combination Control Requirements for ON Semi
48ARM92243A	W	17-Sep-21	MC74HC595A Series
67AON47346E	D	12-Jul-21	MC74HC595AD and MC74HC595AAD

BOM Links

Up/Down Direction	Site	Top Part	Link



Rev	Rev Date	Details
1	2021-DEC-06 11:04:03	Initial version

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